Cheng Hong Tsai 蔡振弘

Title:

TSMC 16nm FinFET+ Chip Implementation Challenges and Experience Sharing

Speaker:

學歷: 清華大學資訊科學所碩士
經歷: 1997~2001 台灣積體電路 CAD 工程師
2001~now 創意電子 實體設計流程部經理

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Abstract:

TSMC 16nm advanced technology node introduces new technologies, FinFET device and double patterning wire, that come with new design and implementation challenges in physical layout realization, timing / power closure, and variation management in various operating conditions.

GUC designs an application platform that integrates SoC design, GUC proprietary and 3rd party IP to realize the design and chip implementation capability in TSMC 16nm FinFET+ technology. This presentation will share GUC solution and experience, including the design flow, implementation guideline, and variation management.